
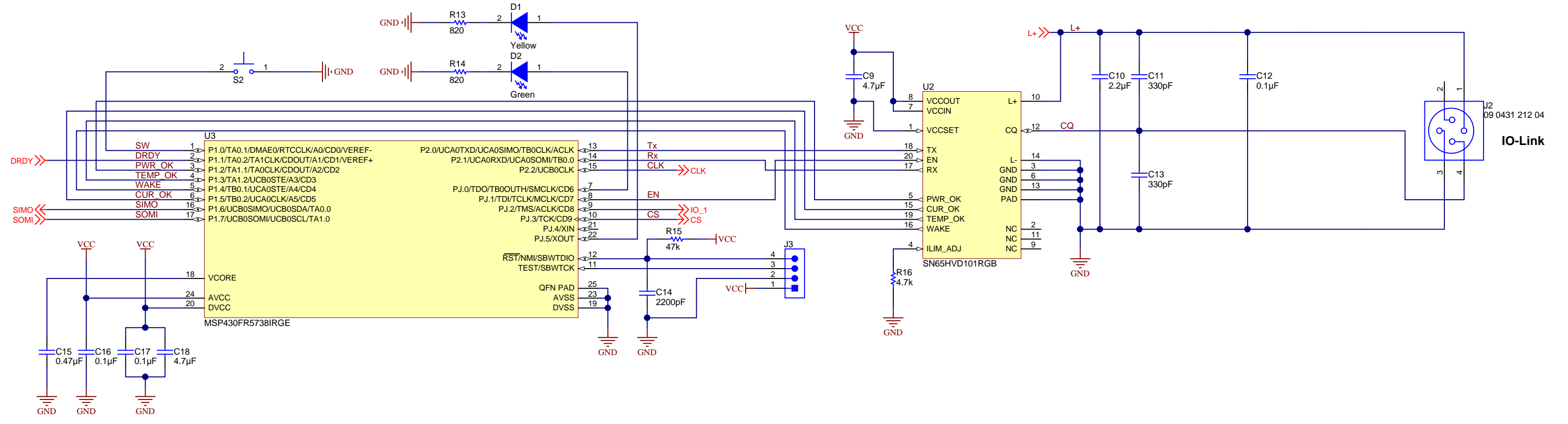
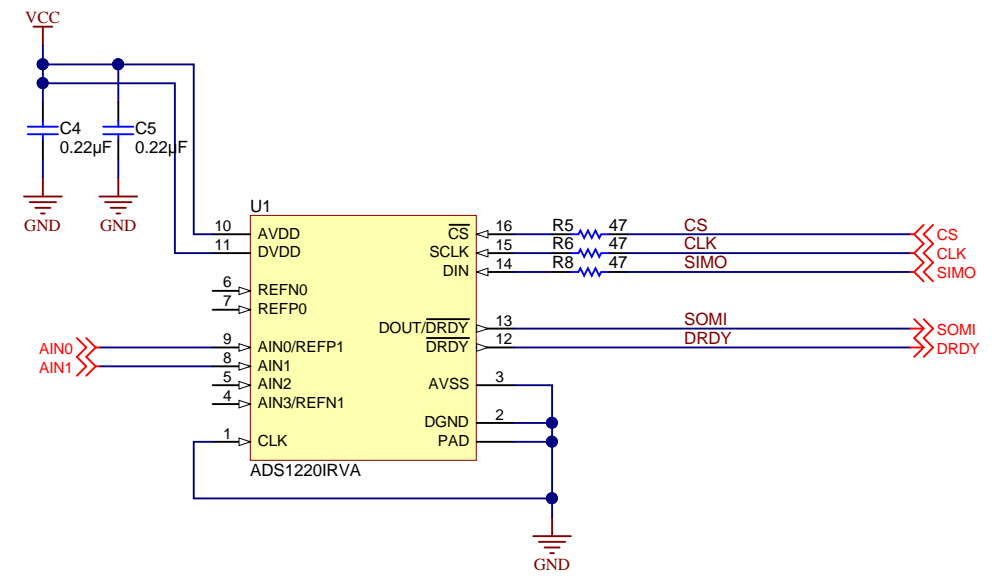
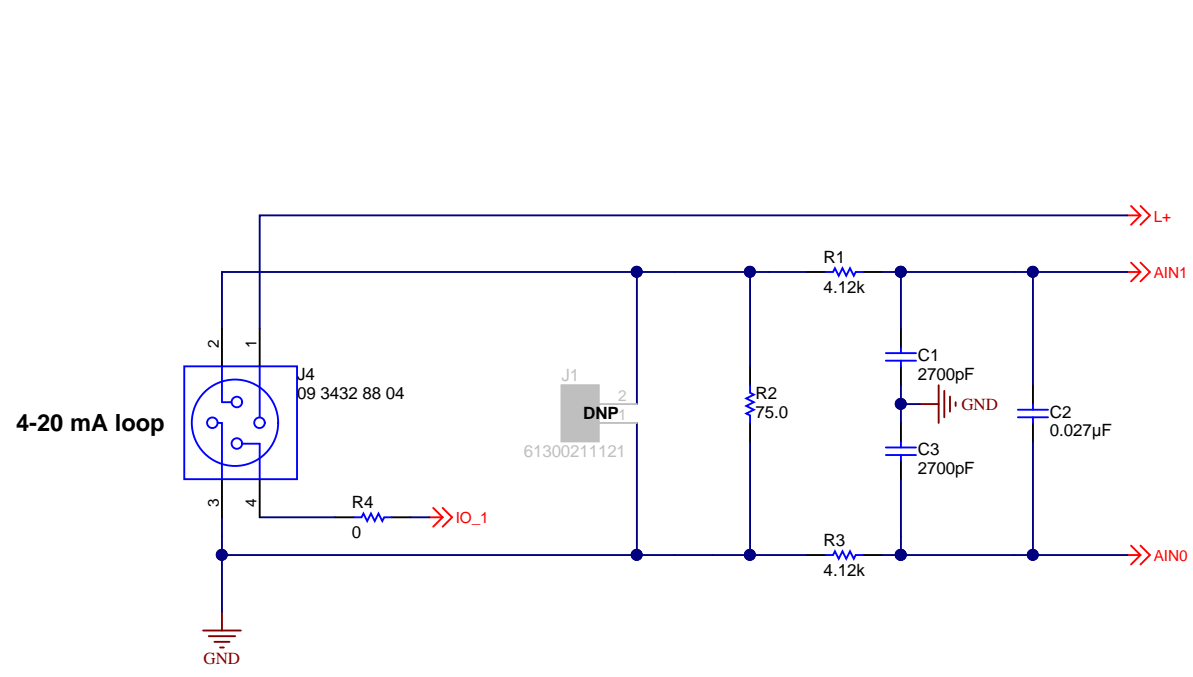


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TID #: TIDA-00457	Project Title: 4-20mA to IO-Link Converter		
Number: TIDA-00457	Rev: E2	Sheet Title: Block Diagram	
SVN Rev: Version control disabled	Assembly Variant: TID	Sheet: 1 of 3	
Drawn By: Thomas Schneider	File: TIDA-00457_CoverSheet_SchDoc	Size: B	
Engineer: Thomas Schneider	Contact: http://www.ti.com/support		



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TID #: TIDA-00457	Project Title: 4-20mA to IO-Link Converter	
Number: TIDA-00457	Rev: E2	Sheet Title: TIDA-00457
SVN Rev: Version control disabled	Assembly Variant: TID	Sheet: 2 of 3
Drawn By: Thomas Schneider	File: TIDA-00457_SchDoc	Size: B
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PCB Number: TIDA-00457
PCB Rev: E2

PCB
LOGO
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PCB
LOGO
Pb-Free Symbol

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 2/29/2016	 TEXAS INSTRUMENTS http://www.ti.com <small>© Texas Instruments 2016</small>
TID #: TIDA-00457	Project Title: 4-20mA to IO-Link Converter		
Number: TIDA-00457	Rev: E2	Sheet: 3 of 3	
SVN Rev: Version control disabled	Assembly Variant: TID	Size: B	
Drawn By: Thomas Schneider	File: TIDA-00457_Hardware.SchDoc	Contact: http://www.ti.com/support	

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